

CS152 – Computer Architecture and Engineering

Lecture 4 – Overview of Logic Design

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CS 152 L04 Logic (1)

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Review

- 4-LUT FPGAs are basically interconnect plus distributed RAM that can be programmed to act as any logical function of 4 inputs
- CAD tools do the partitioning, routing, and placement functions onto CLBs
- FPGAs offer compromise of performance, Non Recurring Engineering, unit cost, time to market vs. ASICs or microprocessors (plus software)

	Performance	NRE	Unit Cost	TTM
Better ↑	ASIC	MICRO	ASIC	MICRO
	FPGA	FPGA	MICRO	FPGA
Worse ↓	MICRO	ASIC	FPGA	ASIC



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Outline

- Critical Path
- Setup / Hold Times
- Clock skew
- Finite State Machines
- One-hot encoding
- DeMorgan's Theorem
- Don't cares/ Karnaugh Maps
- IC costs



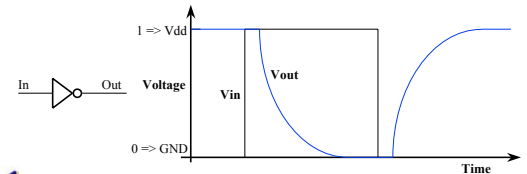
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FPGA CAD guided tour (if time permits)

Ideal versus Reality

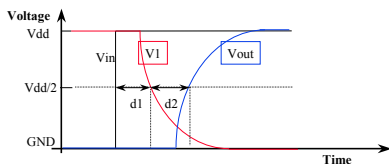
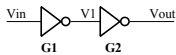
- When input 0 → 1, output 1 → 0 but NOT instantly
 - Output goes 1 → 0: output voltage goes from V_{dd} (5v) to 0v
- When input 1 → 0, output 0 → 1 but NOT instantly
 - Output goes 0 → 1: output voltage goes from 0v to V_{dd} (5v)
- Voltage does not like to change instantaneously



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Series Connection



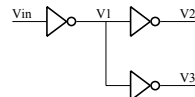
- Total Propagation Delay = Sum of individual delays = $d_1 + d_2$
- Capacitance C1 has two components:
 - Capacitance of the wire connecting the two gates
 - Input capacitance of the second inverter



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Calculating Aggregate Delays; Critical Path



- Sum delays along serial paths
- Delay (Vin → V2) ≠ Delay (Vin → V3)
 - Delay (Vin → V2) = Delay (Vin → V1) + Delay (V1 → V2)
 - Delay (Vin → V3) = Delay (Vin → V1) + Delay (V1 → V3)
- Capacitance₁ = Wire Capacitance + Capacitance_{in} of Invertor₂ + Capacitance_{in} of Invertor₃

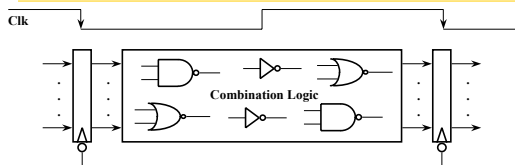
Critical Path = The longest among the N parallel paths



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Clocking Methodology



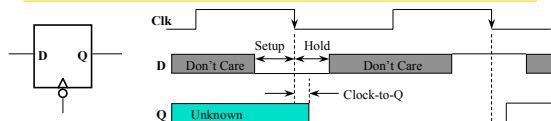
- ° All storage elements are clocked by the same clock edge
- ° The combination logic block's:
 - Inputs are updated at each clock tick
 - All outputs MUST be stable before the next clock tick



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Storage Element's Timing Model



- ° Setup Time: Input must be stable BEFORE trigger clock edge
- ° Hold Time: Input must REMAIN stable after trigger clock edge
- ° Clock-to-Q time:
 - Output cannot change instantaneously at the trigger clock edge
 - Similar to delay in logic gates, two components:
 - Internal Clock-to-Q
 - Load dependent Clock-to-Q

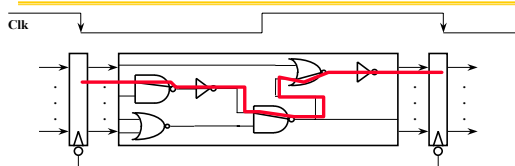
Typical for Virtex-E: ? Setup, ? Hold



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Critical Path & Cycle Time



- ° Critical path: the slowest path between any two storage devices
- ° Cycle time is a function of the critical path
- ° must be greater than:
 - Clock-to-Q + Longest Path through Combination Logic + Setup

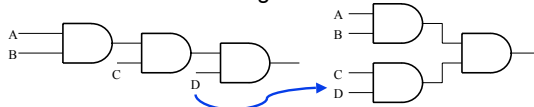


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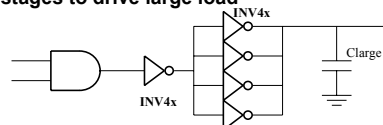
Tricks to Reduce Cycle Time

- ° Reduce the number of gate levels



- ° Pay attention to loading

- ° One gate driving many gates is a bad idea
- ° Avoid using a small gate to drive a long wire
- ° Use multiple stages to drive large load



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Administrivia (1/2)

- ° Even though there is lots of space in the class, there is a mistake in Telebeats that is preventing us from adding people into sections. Therefore, if you are not enrolled in the course, but want to get in, here is what you have to do:
 - ° By Friday 9/5 1:00pm, talk to Michael David Sasson (in person) in 379 Soda
- ° Be sure to tell him which section you want to move into. If you don't talk to him by Friday, we can't add you to the class!



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Administrivia (2/2)

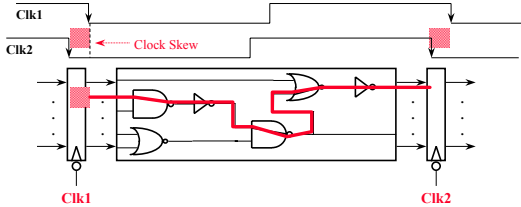
- ° Friday 9/5 lab demo in 125 Cory 3-4
 - If didn't take CS 150, should go to demo
- ° Office hours in Lab
 - Mon 5 – 6:30 Jack, Tue 3:30-5 Kurt, Wed 3 – 4:30 John
- ° Dave's office hours Tue 3:30 – 5
- ° HW #1 Due Wed 9/10
- ° Lab #2 done in pairs since 15 FPGA boards, 33 PCs. Due Monday 9/15
- ° Form 4 or 5 person teams by Friday 9/12



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Clock Skew's Effect on Cycle Time



- ° The worst case scenario for cycle time consideration:
 - The input register sees CLK1
 - The output register sees CLK2

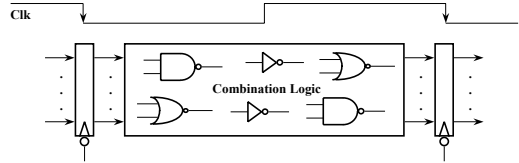
° Cycle Time - Clock Skew \geq CLK-to-Q + Longest Delay + Setup
 \Rightarrow Cycle Time \geq CLK-to-Q + Longest Delay + Setup + Clock Skew



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How to Avoid Hold Time Violation?



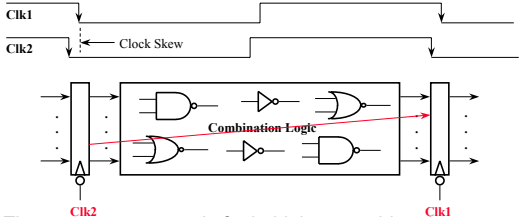
- ° Hold time requirement:
 - Input to register must NOT change immediately after the clock tick
- ° This is usually easy to meet in the "edge trigger" clocking scheme
- ° CLK-to-Q + Shortest Delay Path must be greater than Hold Time



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Clock Skew's Effect on Hold Time



- ° The worst case scenario for hold time consideration:
 - The input register sees CLK2
 - The output register sees CLK1
 - fast FF2 output must not change input to FF1 for same clock edge

° (CLK-to-Q + Shortest Delay Path - Clock Skew) > Hold Time

Danger is one fast path (e.g., 1 gate) violate hold time



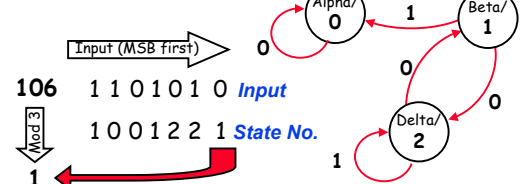
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Finite State Machines:

- ° System state is explicit in representation
- ° Transitions between states represented as arrows with inputs on arcs
- ° Output may be either part of state or on arcs

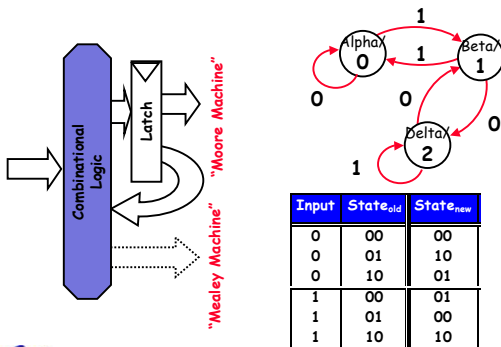
"Mod 3 Machine"



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FSM Implementation as Combinational logic + Latch



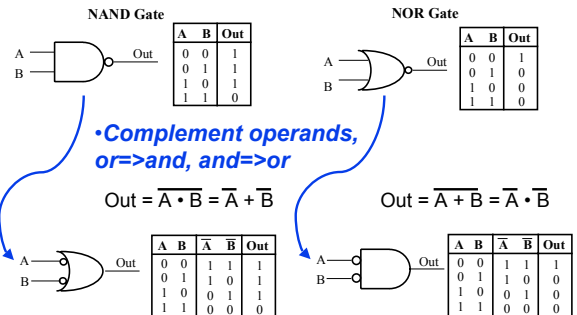
Input	State _{old}	State _{new}
0	00	00
0	01	10
0	10	01
1	00	01
1	01	00
1	10	10



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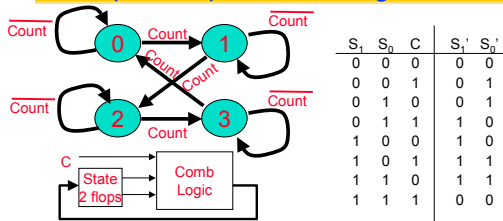
DeMorgan's theorem: Push Bubbles and Morph



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Example: Simplification of logic



$$S_0' = (\overline{S_1} \cdot \overline{S_0} \cdot C) + (\overline{S_1} \cdot S_0 \cdot \overline{C}) + (S_1 \cdot \overline{S_0} \cdot C) + (S_1 \cdot S_0 \cdot \overline{C})$$

$$= (\overline{S_0} \cdot C) + (S_0 \cdot \overline{C})$$

$$S_1' = (\overline{S_1} \cdot S_0 \cdot C) + (S_1 \cdot \overline{S_0} \cdot \overline{C}) + (S_1 \cdot \overline{S_0} \cdot C) + (S_1 \cdot S_0 \cdot \overline{C})$$

$$= (\overline{S_1} \cdot S_0 \cdot C) + (S_1 \cdot \overline{C}) + (S_1 \cdot S_0)$$

Karnaugh Map for easier simplification

Group Ones in powers of 2, simplify, OR-together

S_1	S_0	C	S_1'	S_0'
0	0	0	0	0
0	0	1	0	1
0	1	0	0	1
0	1	1	1	0
1	0	0	1	0
1	0	1	1	1
1	1	0	1	1
1	1	1	0	0

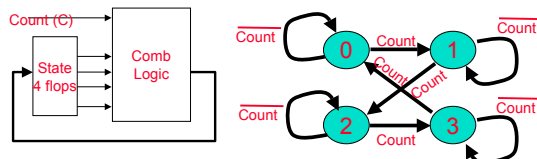
		$S_1 S_0$			
S_0'		00	01	11	10
C	0	0	1	1	0
	1	1	0	0	1

$$S_0' = (\overline{S_0} \cdot C) + (S_0 \cdot \overline{C})$$

	S_1'	$S_1 S_0$			
		00	01	11	10
C	0	0	0	1	1
	1	0	1	0	1

$$S_1' = (\overline{S_1} \cdot S_0 \cdot C) + (S_1 \cdot \overline{C}) + (S_1 \cdot S_0)$$

"One-Hot Encoding": 1 FF/state vs. \log_2 FFs



- One Flip-flop per state
=> no decode HW of state no.
- Only one state bit = 1 at a time
- Much faster combinational logic
- Tradeoff: Size \leftrightarrow Speed

$$S_0' = (S_0 \cdot \overline{C}) + (S_3 \cdot C)$$

$$S_1' = (S_1 \cdot \overline{C}) + (S_0 \cdot C)$$

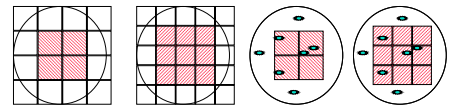
$$S_2' = (S_2 \cdot \overline{C}) + (S_1 \cdot C)$$

$$S_3' = (S_3 \cdot \overline{C}) + (S_2 \cdot C)$$

Integrated Circuit Costs

$$\text{Die cost} = \frac{\text{Wafer cost}}{\text{Dies per Wafer} \cdot \text{Die yield}}$$

$$\text{Dies per wafer} = \frac{\pi \cdot (\text{Wafer diam} / 2)^2}{\text{Die Area}} - \frac{\pi \cdot \text{Wafer diam}}{\sqrt{2 \cdot \text{Die Area}}} - \text{Test dies} \approx \frac{\text{Wafer Area}}{\text{Die Area}}$$



$$\text{Die Yield} = \frac{\text{Wafer yield}}{\{1 + \frac{\text{Defects per unit area} \cdot \text{Die Area}}{\alpha}\}^\alpha}$$

Die Cost is roughly polynomial with the size: (die area)³ or (die area)⁴

Real World Examples: 2003

Feature	Blackfin BCM1150	IBM 440GX	Intel Pentium 4	Motorola MPC7447	Motorola MPC7447	NEC V87201	PMC RM9000/2GL	Toshiba 4955CEG
Architecture	Enhanced MIPS64	PowerPC Book E	PowerPC 7447	PowerPC 7447	PowerPC 7447	MIPS IV + extensions	Enhanced MIPS64	MIPS III
Core Freq (MHz)	600-800	500-800	2GHz	1.3GHz	833	400	1,000	400
Bus Freq (MHz)	200	166	200	167	166	200 (DDR)	200	133
Cache (1/D)	32K/32K	32K/32K	16K/16K	32K/32K	32K/32K	32K/32K	32K/32K	32K/32K
Level 2 Cache	512K	256K	1M	512K	256K	256K	512K	No
FPU	Yes	No	No	Yes	Yes	Yes	Yes	Yes
Pipeline Stages	8-9	7	8-12	7	7	10	7	5
Instructions per Clock	4	2	1	3+branch	3+branch	2	2	1
Special Features	Dual com. Hyper-transport, 10/100/1,000 Ethernet	10/100/1,000 Ethernet, TCP/IP acceleration, PCI-X	RapidIO, SMD-444 multi-processor unit	AltVec	RapidIO, 2x10/100/1,000 Ethernet, PCI-X, DDR, CMA	Out of order execution	Dual com. Hyper-transport, 3 10/100/1,000 Ethernet ports	One of first 90nm chips
Voltage (core)	1.2	1.5	1	1.3	1.2	1.5	1.2	1.2
Power (typ)	10W	4.5W@3.3MHz	13.5W	7.5W@1GHz	5W	4W	12W	0.6W
Transistors (millions)	~60	DTP	68M	58	DTP	6.5	50	5
IC Process	0.13um	0.13um	0.13um	0.13um	0.13um	0.13um	0.13um	0.13um
Die Size (mm ²)	DTP	DTP	122	98	DTP	128.2	128.2	20.83
Availability	Now	Sampling	Sampling	ES: Now	Sampling now	Sampling	Sampling	Sampling
Price (10K)	\$499	\$71 (500MHz)	\$149	\$189	\$129	\$90	\$179	\$22

From "Chart Watch: Embedded Processors," Microprocessor Report, August 25, 2003

Die Yield : 1995 data

wafer diameter	die area (mm ²)	196	256	324	400
6"/15cm	139	90	62	44	32
8"/20cm	265	177	124	90	68
10"/25cm	431	290	206	153	116

die yield	23%	19%	16%	12%	11%	10%
-----------	-----	-----	-----	-----	-----	-----

typical CMOS process: $\alpha = 2$, wafer yield=90%, defect density=2/cm², 4 test sites/wafer

Good Dice Per Wafer (Before Testing!)

6"/15cm	31	16	9	5	3	2
8"/20cm	59	32	19	11	7	5
10"/25cm	96	53	32	20	13	9

typical cost of an 8", 4 metal layers, 0.5um CMOS wafer: ~\$2000

Real World Examples: 1993

Chip	Metal layers	Line width	Wafer cost	Defect /cm ²	Area mm ²	Dies/ wafer	Yield	Die Cost
386DX	2	0.90	\$900	1.0	43	360	71%	\$4
486DX2	3	0.80	\$1200	1.0	81	181	54%	\$12
PowerPC 601	4	0.80	\$1700	1.3	121	115	28%	\$53
HP PA 7100	3	0.80	\$1300	1.0	196	66	27%	\$73
DEC Alpha	3	0.70	\$1500	1.2	234	53	19%	\$149
SuperSPARC	3	0.70	\$1700	1.6	256	48	13%	\$272
Pentium	3	0.80	\$1500	1.5	296	40	9%	\$417

From "Estimating IC Manufacturing Costs," by Linley Gwennap, *Microprocessor Report*, August 2, 1993, p. 15

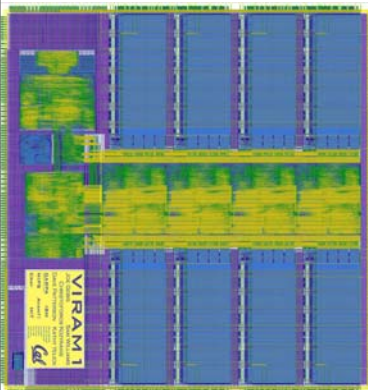
Other Costs

$$\text{IC cost} = \frac{\text{Die cost} + \text{Testing cost} + \text{Packaging cost}}{\text{Final test yield}}$$

Packaging Cost: depends on pins, heat dissipation

Chip	Die cost	Pins	Package type	Package cost	Test & Assembly	Total
386DX	\$4	132	QFP	\$1	\$4	\$9
486DX2	\$12	168	PGA	\$11	\$12	\$35
PowerPC 601	\$53	304	QFP	\$3	\$21	\$77
HP PA 7100	\$73	504	PGA	\$35	\$16	\$124
DEC Alpha	\$149	431	PGA	\$30	\$23	\$202
SuperSPARC	\$272	293	PGA	\$20	\$34	\$326
Pentium	\$417	273	PGA	\$19	\$37	\$473

Berkeley Vector IRAM chip: 2003



- ° MIPS CPU + multimedia coprocessor + 104 Mbits (13 Mbytes) of on-chip main memory
- ° 2 W, 200 MHz
- ° Die size: 325 mm², in 0.18 micron, 125M transistors
- ° App: future PDAs

Peer Instruction

- ° Which of the following are **false**?

1. $\overline{(A + B)} \cdot \overline{(C + D)} = (\overline{A} \cdot \overline{B}) + (\overline{C} + \overline{D})$
2. Clock skew can lead to setup time violations
3. Clock skew can lead to hold time violations
4. If the die size is doubled, the cost of the die is roughly quadrupled

In conclusion, Logic review ...

- ° **Critical Path** is longest among N parallel paths
- ° **Setup Time** and **Hold Time** determine how long Input must be stable before and after trigger clock edge
- ° **Clock skew** is difference between clock edge in different parts of hardware; it affects clock cycle time and can cause hold time, setup time violations
- ° **FSM** specify control symbolically
 - Moore machine easiest to understand, debug
 - "One shot" reduces decoding for faster FSM
- ° Die size affects both dies/wafer and yield